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DICTIONARY FILE UPDATES:  20 FEB 2008  HIGHEST RN 1004854-20-9

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http://www.cas.org/support/stngen/stndoc/properties.html

=> d ide can tot l5

L5   ANSWER 1 OF 3  REGISTRY  COPYRIGHT 2008 ACS on STN
RN   851539-16-7  REGISTRY
ED   Entered STN:  02 Jun 2005
CN   Phenol, 3,3'-[(1,1,3,3-tetramethyl-1,3-disiloxanediyl)di-3,1-
     propanediyl]bis- (9CI)  (CA INDEX NAME)
MF   C22 H34 O3 Si2
SR   CA
LC   STN Files:   CA, CAPLUS, USPATFULL
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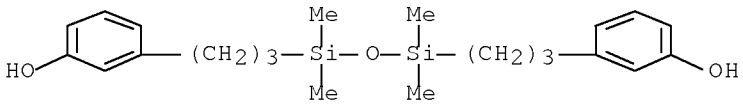


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**PROPERTY DATA AVAILABLE IN THE 'PROP' FORMAT**

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               1 REFERENCES IN FILE CAPLUS (1907 TO DATE)

REFERENCE   1:  142:464516

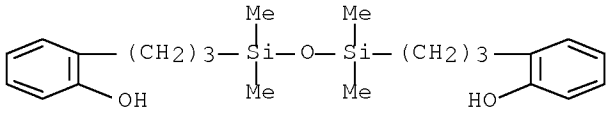
L5   ANSWER 2 OF 3  REGISTRY  COPYRIGHT 2008 ACS on STN
RN   60338-33-2  REGISTRY
ED   Entered STN:  16 Nov 1984
CN   Carbonic dichloride, polymer with 2,2'-[(1,1,3,3-tetramethyl-1,3-
     disiloxanediyl)di-3,1-propanediyl]bis[phenol] (9CI)  (CA INDEX NAME)
OTHER CA INDEX NAMES:
```

CN Phenol, 2,2'-[(1,1,3,3-tetramethyl-1,3-disiloxanediyl)di-3,1-propanediyl]bis-, polymer with carbonic dichloride (9CI)
OTHER NAMES:
CN 1,3-Bis[γ-(o-hydroxyphenyl)propyl]-1,1,3,3-tetramethyldisiloxane-phosgene copolymer
MF (C22 H34 O3 Si2 . C Cl2 O)x
CI PMS
PCT Polycarbonate, Polycarbonate formed
LC STN Files: CA, CAPLUS

RELATED POLYMERS AVAILABLE WITH POLYLINK

CM 1

CRN 4515-51-9
CMF C22 H34 O3 Si2



CM 2

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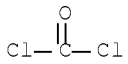
CMF C Cl2 O

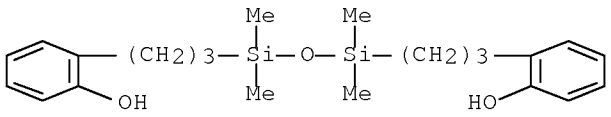


2 REFERENCES IN FILE CA (1907 TO DATE)
2 REFERENCES IN FILE CAPLUS (1907 TO DATE)

REFERENCE 1: 87:185014

REFERENCE 2: 85:109031

L5 ANSWER 3 OF 3 REGISTRY COPYRIGHT 2008 ACS on STN
RN 4515-51-9 REGISTRY
ED Entered STN: 16 Nov 1984
CN Phenol, 2,2'-[(1,1,3,3-tetramethyl-1,3-disiloxanediyl)di-3,1-propanediyl]bis- (9CI) (CA INDEX NAME)
OTHER CA INDEX NAMES:
CN Phenol, 2,2'-[(tetramethyldisiloxanylene)bis(trimethylene)]di- (7CI, 8CI)
OTHER NAMES:
CN 1,3-Bis[(γ-ortho-hydroxyphenyl)propyl]-1,1,3,3-tetramethyl disiloxane
MF C22 H34 O3 Si2
CI COM
LC STN Files: BEILSTEIN*, CA, CAOLD, CAPLUS, USPAT2, USPATFULL
(*File contains numerically searchable property data)



PROPERTY DATA AVAILABLE IN THE 'PROP' FORMAT

12 REFERENCES IN FILE CA (1907 TO DATE)
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12 REFERENCES IN FILE CAPLUS (1907 TO DATE)
1 REFERENCES IN FILE CAOLD (PRIOR TO 1967)

REFERENCE 1: 145:490036

REFERENCE 2: 138:402371

REFERENCE 3: 136:184218

REFERENCE 4: 120:193643

REFERENCE 5: 120:9729

REFERENCE 6: 82:17156

REFERENCE 7: 79:42603

REFERENCE 8: 76:153842

REFERENCE 9: 76:46295

REFERENCE 10: 76:4464

=> fil uspatful
FILE 'USPATFULL' ENTERED AT 13:53:19 ON 21 FEB 2008
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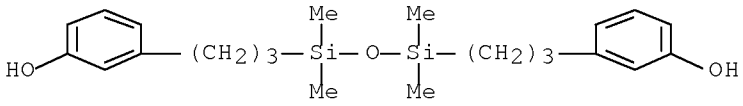
FILE COVERS 1971 TO PATENT PUBLICATION DATE: 21 Feb 2008 (20080221/PD)
FILE LAST UPDATED: 21 Feb 2008 (20080221/ED)
HIGHEST GRANTED PATENT NUMBER: US7334268
HIGHEST APPLICATION PUBLICATION NUMBER: US2008047040
CA INDEXING IS CURRENT THROUGH 21 Feb 2008 (20080221/UPCA)
ISSUE CLASS FIELDS (/INCL) CURRENT THROUGH: 21 Feb 2008 (20080221/PD)
REVISED CLASS FIELDS (/NCL) LAST RELOADED: Dec 2007
USPTO MANUAL OF CLASSIFICATIONS THESAURUS ISSUE DATE: Dec 2007

=> d bib abs hitstr tot l35

L35 ANSWER 1 OF 8 USPATFULL on STN
AN 2007:257492 USPATFULL Full-text
TI Curable Silicone Composition and Cured Product Thereof
IN Morita, Yoshitsugu, Chiba Prefecture, JAPAN
Isshiki, Minoru, Ehime Prefecture, JAPAN
Ueki, Hiroshi, Chiba Prefecture, JAPAN
Togashi, Atsushi, Midland, MI, UNITED STATES

PI US 2007225437 A1 20070927
AI US 2004-578798 A1 20041104 (10)
WO 2004-JP16716 20041104
20070112 PCT 371 date
PRAI JP 2003-378521 20031107
DT Utility
FS APPLICATION
LREP HOWARD & HOWARD ATTORNEYS, P.C., THE PINEHURST OFFICE CENTER, SUITE #101, 39400 WOODWARD AVENUE, BLOOMFIELD HILLS, MI, 48304-5151, US
CLMN Number of Claims: 18
ECL Exemplary Claim: 1
DRWN No Drawings
LN.CNT 801
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
AB A curable silicone composition includes: (A) an organopolysiloxane represented by the siloxane unit formula (1) given below and having at least two univalent organic groups that contain epoxy groups and are free of aromatic rings: [R.sup.1.sub.3SiO.sub.1/2].sub.a [R.sup.2.sub.2SiO.sub.2/2].sub.b [R.sup.3SiO.sub.3/2].sub.c (where R.sup.1, R.sup.2, and R.sup.3 are univalent organic groups, at least two of which are contain epoxy groups and are free of aromatic rings; more than 20 mole % of R.sup.3 are aryl groups; a+b+c & equals; 1; on average, "a" satisfies the following condition: 0≤a≤0.8; on average, "b" satisfies the following condition: 0≤b≤0.8; and, on average satisfies the following condition: 0.2≤c≤1.0); (B) a linear-chain organopolysiloxane having at least two univalent organic groups that contain phenolic hydroxyl groups; and (C) a curing accelerator.

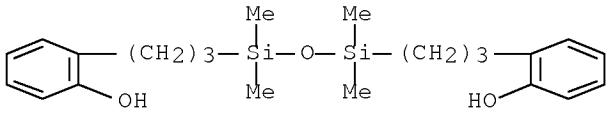
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
IT 851539-16-7
(component B; tri-component curable silicone composition with accelerated curability as sealant/adhesive for electronics with high flexibility and improved adhesion characteristics)
RN 851539-16-7 USPATFULL
CN Phenol, 3,3'-[(1,1,3,3-tetramethyl-1,3-disiloxanediyl)di-3,1-propanediyl]bis- (9CI) (CA INDEX NAME)



L35 ANSWER 2 OF 8 USPATFULL on STN
AN 2004:162477 USPATFULL Full-text
TI Benzoxazines, thermosetting resins comprised thereof, and methods for use thereof
IN Dershem, Stephen M., San Diego, CA, UNITED STATES
Liu, Puwei, San Diego, CA, UNITED STATES
Mizori, Farhad G., La Mesa, CA, UNITED STATES
PA Loctite Corporation (U.S. corporation)
PI US 2004123948 A1 20040701
AI US 2003-735119 A1 20031211 (10)
RLI Division of Ser. No. US 2001-8591, filed on 13 Nov 2001, PENDING
DT Utility

FS APPLICATION
LREP FOLEY & LARDNER, P.O. BOX 80278, SAN DIEGO, CA, 92138-0278
CLMN Number of Claims: 19
ECL Exemplary Claim: 1
DRWN No Drawings
LN.CNT 930
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
AB In accordance with the present invention, there are provided novel benzoxazine compounds and thermosetting resin compositions prepared therefrom. Invention compositions are particularly useful for increasing adhesion at interfaces within microelectronic packages. Invention benzoxazines are useful for the preparation of invention compositions with properties which are associated with increased adhesion at interfaces, such as, for example, low shrinkage on cure and low coefficient of thermal expansion (CTE). In another aspect of the invention, there are provided die-attach pastes having increased interfacial adhesion. Invention die-attach pastes include benzoxazine-containing thermosetting resin compositions. In further aspects of the invention, there are provided methods for enhancing adhesive strength of thermosetting resin compositions and methods for enhancing adhesion of a substrate bound to a metallic surface by a thermosetting resin composition.

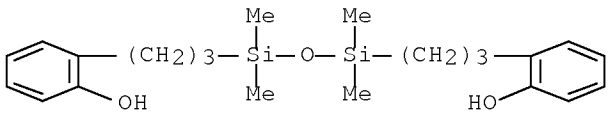
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
IT 4515-51-9P
(intermediate; for polymerizable benzoxazines for adhesives)
RN 4515-51-9 USPATFULL
CN Phenol, 2,2'-[(1,1,3,3-tetramethyl-1,3-disiloxanediyl)di-3,1-propanediyl]bis- (9CI) (CA INDEX NAME)



L35 ANSWER 3 OF 8 USPATFULL on STN
AN 2003:181717 USPATFULL Full-text
TI Benzoxazines, thermosetting resins comprised thereof, and methods for use thereof
IN Dershem, Stephen M., San Diego, CA, UNITED STATES
Liu, Puwei, San Diego, CA, UNITED STATES
Mizori, Farhad G., La Mesa, CA, UNITED STATES
PA Loctite Corporation (U.S. corporation)
PI US 2003125551 A1 20030703
US 6743852 B2 20040601
AI US 2001-8591 A1 20011113 (10)
DT Utility
FS APPLICATION
LREP FOLEY & LARDNER, P.O. BOX 80278, SAN DIEGO, CA, 92138-0278
CLMN Number of Claims: 35
ECL Exemplary Claim: 1
DRWN No Drawings
LN.CNT 935
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
AB In accordance with the present invention, there are provided novel benzoxazine compounds and thermosetting resin compositions prepared

therefrom. Invention compositions are particularly useful for increasing adhesion at interfaces within microelectronic packages. Invention benzoxazines are useful for the preparation of invention compositions with properties which are associated with increased adhesion at interfaces, such as, for example, low shrinkage on cure and low coefficient of thermal expansion (CTE). In another aspect of the invention, there are provided die-attach pastes having increased interfacial adhesion. Invention die-attach pastes include benzoxazine-containing thermosetting resin compositions. In further aspects of the invention, there are provided methods for enhancing adhesive strength of thermosetting resin compositions and methods for enhancing adhesion of a substrate bound to a metallic surface by a thermosetting resin composition.

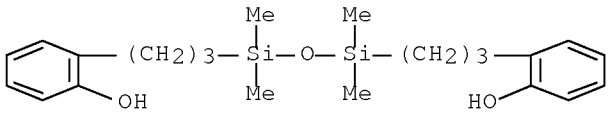
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
IT 4515-51-9P
(intermediate; for polymerizable benzoxazines for adhesives)
RN 4515-51-9 USPATFULL
CN Phenol, 2,2'-[(1,1,3,3-tetramethyl-1,3-disiloxanediyl)di-3,1-propanediyl]bis- (9CI) (CA INDEX NAME)



L35 ANSWER 4 OF 8 USPATFULL on STN
AN 94:57936 USPATFULL Full-text
TI Aromatic cyanate-siloxane
IN Liao, Zeng K., Lake Jackson, TX, United States
Wang, Chun S., Tainan, Taiwan, Province of China
PA The Dow Chemical Company, Midland, MI, United States (U.S. corporation)
PI US 5326893 19940705
AI US 1993-147279 19931027 (8)
RLI Division of Ser. No. US 1993-93497, filed on 16 Jul 1993 which is a division of Ser. No. US 1992-837464, filed on 14 Feb 1992, now patented, Pat. No. US 5260398 which is a continuation-in-part of Ser. No. US 1990-505310, filed on 5 Apr 1990, now abandoned
DT Utility
FS Granted
EXNAM Primary Examiner: Marquis, Melvyn I.; Assistant Examiner: Dean, Karen A.
CLMN Number of Claims: 4
ECL Exemplary Claim: 1
DRWN No Drawings
LN.CNT 901
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
AB Compounds are prepared which have at least one aromatic cyanate group and at least one organosiloxane moiety per molecule. These compounds when cured possess excellent thermal stability, moisture resistance properties and a low dielectric constant.

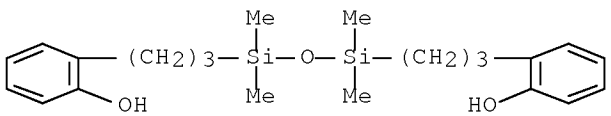
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
IT 4515-51-9P
(preparation and reaction of, for curable cyanato siloxane compns.)
RN 4515-51-9 USPATFULL

CN Phenol, 2,2'-[(1,1,3,3-tetramethyl-1,3-disiloxanediyl)di-3,1-propanediyl]bis- (9CI) (CA INDEX NAME)



L35 ANSWER 5 OF 8 USPATFULL on STN
AN 94:28835 USPATFULL Full-text
TI Blends containing cyanate-siloxanes
IN Liao, Zeng K., Lake Jackson, TX, United States
Wang, Chun S., Tainan, Taiwan, Province of China
PA The Dow Chemical Company, Midland, MI, United States (U.S. corporation)
PI US 5300591 19940405
AI US 1993-93497 19930716 (8)
RLI Division of Ser. No. US 1992-837464, filed on 14 Feb 1992, now patented, Pat. No. US 5260398 which is a continuation-in-part of Ser. No. US 1990-505310, filed on 5 Apr 1990, now abandoned
DT Utility
FS Granted
EXNAM Primary Examiner: Marquis, Melvyn I.; Assistant Examiner: Dean, Karen A.
CLMN Number of Claims: 5
ECL Exemplary Claim: 1
DRWN No Drawings
LN.CNT 850
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
AB Blends containing (1) at least one compound containing an average of more than one vicinal aromatic cyanate group per molecule and at least one organosiloxane moiety per molecule and (2) at least one compound containing an average of more than one vicinal aromatic cyanate group per molecule which is substantially free of organosiloxane moieties. The compositions are useful as a component in adhesives, coatings, laminates, composites, encapsulants, filament winding, and molding.

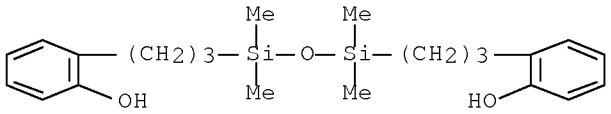
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
IT 4515-51-9P
(preparation and reaction of, for curable cyanato siloxane compns.)
RN 4515-51-9 USPATFULL
CN Phenol, 2,2'-[(1,1,3,3-tetramethyl-1,3-disiloxanediyl)di-3,1-propanediyl]bis- (9CI) (CA INDEX NAME)



L35 ANSWER 6 OF 8 USPATFULL on STN
AN 93:93887 USPATFULL Full-text
TI Aromatic cyanate-siloxane

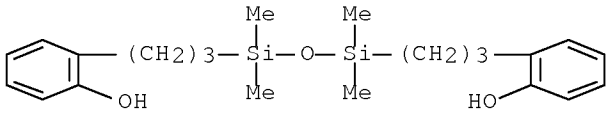
IN Liao, Zeng K., Lake Jackson, TX, United States
Wang, Chun S., Tainan, Taiwan, Province of China
PA The Dow Chemical Company, Midland, MI, United States (U.S. corporation)
PI US 5260398 19931109
AI US 1992-837464 19920214 (7)
RLI Continuation-in-part of Ser. No. US 1990-505310, filed on 5 Apr 1990, now abandoned
DT Utility
FS Granted
EXNAM Primary Examiner: Marquis, Melvyn I.; Assistant Examiner: Dean, Karen A.
CLMN Number of Claims: 10
ECL Exemplary Claim: 1
DRWN No Drawings
LN.CNT 881
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
AB Curable compositions containing a compound containing an average of more than one vicinal aromatic cyanate group per molecule and at least one organosiloxane moiety per molecule and a curing catalyst therefor. The compositions are useful as a component in adhesives, coatings, laminates, composites, encapsulants, filament winding, and molding.

CAS INDEXING IS AVAILABLE FOR THIS PATENT.
IT 4515-51-9P
(preparation and reaction of, for curable cyanato siloxane compns.)
RN 4515-51-9 USPATFULL
CN Phenol, 2,2'-[(1,1,3,3-tetramethyl-1,3-disiloxanediyl)di-3,1-propanediyl]bis- (9CI) (CA INDEX NAME)



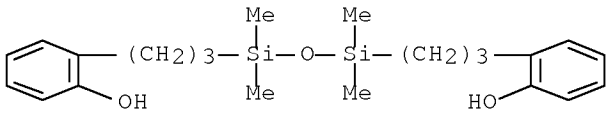
L35 ANSWER 7 OF 8 USPATFULL on STN
AN 93:33565 USPATFULL Full-text
TI Aromatic hydroxyl-containing compounds containing organosiloxane moieties, epoxy compounds and cured products thereof
IN Liao, Zeng K., Lake Jackson, TX, United States
Wang, Chun S., Tainan, Taiwan, Province of China
PA The Dow Chemical Company, Midland, MI, United States (U.S. corporation)
PI US 5206312 19930427
AI US 1991-729508 19910712 (7)
RLI Continuation-in-part of Ser. No. US 1989-439208, filed on 20 Nov 1989, now abandoned
DT Utility
FS Granted
EXNAM Primary Examiner: Bleutge, John C.; Assistant Examiner: Glass, M. W.
CLMN Number of Claims: 25
ECL Exemplary Claim: 1
DRWN No Drawings
LN.CNT 1755
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
AB Compounds are prepared which contain both an organosiloxane moiety and either a phenolic hydroxyl group or an epoxide group. Also disclosed are curable and cured compositions.

CAS INDEXING IS AVAILABLE FOR THIS PATENT.
IT 4515-51-9DP, polymers with epoxy cresol novolac resins
(preparation of, with high thermal stability)
RN 4515-51-9 USPATFULL
CN Phenol, 2,2'-[(1,1,3,3-tetramethyl-1,3-disiloxanediyl)di-3,1-propanediyl]bis- (9CI) (CA INDEX NAME)



L35 ANSWER 8 OF 8 USPATFULL on STN
AN 71:43868 USPATFULL Full-text
TI METHOD OF PREPARING 1,3-BIS/HYDROXYALKYL(ARYL)/-TETRAORGANODISILOXANES
IN Mironov, Vladimir Florovich, UL. Gubkina, 4, kv. 13, Moscow, USSR
Kozlikov, Vadim Lvovich, Novye Cheremushki, Korpus 19, kv. 15, Moscow, USSR
PI US 3622609 19711123
AI US 1968-754449 19680821 (4)
PRAI SU 1967-1182274 19670823
DT Utility
FS Granted
EXNAM Primary Examiner: Levow, Tobias E.; Assistant Examiner: Shaver, P. F.
LREP Waters, Roditi, Schwartz & Nissen
CLMN Number of Claims: 13
DRWN No Drawings
LN.CNT 281
CAS INDEXING IS AVAILABLE FOR THIS PATENT.
AB Carbofunctional diols of the disiloxane series are prepared by reacting organohalosilanes with unsaturated alcohols in the presence of a tertiary amine as hydrogen chloride acceptor, and in an organic solvent medium, subjecting the resultant alkenyloxydiorganosilanes to polymerization in the presence of a hydrosilylation catalyst, boiling the mixture of siloxyalkanes thus obtained with an alkaline solution, and thereafter separating the desired product.

CAS INDEXING IS AVAILABLE FOR THIS PATENT.
IT 4515-51-9P
(preparation of)
RN 4515-51-9 USPATFULL
CN Phenol, 2,2'-[(1,1,3,3-tetramethyl-1,3-disiloxanediyl)di-3,1-propanediyl]bis- (9CI) (CA INDEX NAME)



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=> fil hcaplus
FILE 'HCAPLUS' ENTERED AT 13:53:36 ON 21 FEB 2008
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FILE LAST UPDATED: 20 Feb 2008  (20080220/ED)

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FILE COVERS 1907 - 21 Feb 2008  VOL 148 ISS 8
FILE LAST UPDATED: 20 Feb 2008  (20080220/ED)

New CAS Information Use Policies, enter HELP USAGETERMS for details.

 This file contains CAS Registry Numbers for easy and accurate
 substance identification.

=> d bib abs hitstr retable tot l33

L33  ANSWER 1 OF 5  HCAPLUS  COPYRIGHT 2008 ACS on STN
AN   2006:1176371  HCAPLUS  Full-text
DN   145:490036
TI   Thermally conductive curable silicone composition and cured product
     therefrom
IN   Morita, Yoshitsugu; Isshiki, Minoru; Ueki,
```

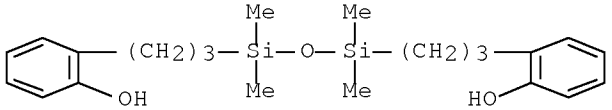
Hiroshi
PA Dow Corning Toray Co., Ltd., Japan
SO PCT Int. Appl., 27pp.
CODEN: PIXXD2
DT Patent
LA English
FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	WO 2006118334	A1	20061109	WO 2006-JP309218	20060427
	W: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, KE, KG, KM, KN, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, LY, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NG, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SM, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW				
	RW: AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, LV, MC, NL, PL, PT, RO, SE, SI, SK, TR, BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG, BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW, AM, AZ, BY, KG, KZ, MD, RU, TJ, TM				
	JP 2006306953	A	20061109	JP 2005-129441	20050427
	EP 1874869	A1	20080109	EP 2006-746050	20060427
	R: AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LI, LT, LU, LV, MC, NL, PL, PT, RO, SE, SI, SK, TR				
	KR 2008003835	A	20080108	KR 2007-724672	20071026
PRAI	JP 2005-129441	A	20050427		
	WO 2006-JP309218	W	20060427		

AB A curable silicone composition comprises: (A) an organopolysiloxane that is represented by the average unit formula: (R13SiO1/2)a(R22SiO2/2)b(R3SiO3/2)c(SiO4/2)d (wherein R1, R2, and R3 are each independently selected from substituted or unsubstituted monovalent hydrocarbon groups and epoxy-functional monovalent organic groups, with the proviso that at least 20 mol% of R3 are aryl groups, and a, b, c, and d are nos. that satisfy $0 \leq a \leq 0.8$, $0 \leq b \leq 0.8$, $0.2 \leq c \leq 0.9$, $0 \leq d < 0.8$, and $a + b + c + d = 1$), and that has at least two of the aforementioned epoxy-functional monovalent organic groups in each mol.; (B) a compound that has a group capable of reacting with the epoxy group; (C) a cure accelerator; and (D) a thermally conductive filler (e.g., silver powder). The composition has excellent handling characteristics and cures rapidly to give a cured product that is highly thermally conductive, very flexible, highly adhesive, and very flame retardant.

IT 4515-51-9
RL: POF (Polymer in formulation); TEM (Technical or engineered material use); USES (Uses)
(thermally conductive curable silicone composition and cured product therefrom)

RN 4515-51-9 HCAPLUS
CN Phenol, 2,2'-[(1,1,3,3-tetramethyl-1,3-disiloxanediyl)di-3,1-propanediyl]bis- (9CI) (CA INDEX NAME)



RETABLE

Referenced Author (RAU)	Year (RPY)	VOL (RVL)	PG (RPG)	Referenced Work (RWK)	Referenced File
Anon	1995	1995		PATENT ABSTRACTS OF	
Anon	1997	1997		PATENT ABSTRACTS OF	
Iwona, R	2003			US 2003212230 A1	HCAPLUS
Morita, Y	2005			WO 2005044920 A	HCAPLUS
Sumitomo Bakelite Co Lt	1995			JP 07161740 A	HCAPLUS
Sumitomo Bakelite Co Lt	1997			JP 09095651 A	HCAPLUS

L33 ANSWER 2 OF 5 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 2005:429487 HCAPLUS Full-text
DN 142:464516
TI Curable silicone composition with accelerated curability as a sealant/adhesive for electronics with high flexibility and improved adhesion characteristics
IN Morita, Yoshitsugu; Isshiki, Minoru; Ueki, Hiroshi; Togashi, Atsushi
PA Dow Corning Toray Silicone Co., Ltd., Japan
SO PCT Int. Appl., 18 pp.
CODEN: PIXXD2
DT Patent
LA English
FAN.CNT 1

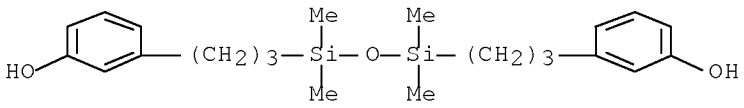
	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	WO 2005044920	A1	20050519	WO 2004-JP16716	20041104
	W: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW				
	RW: BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW, AM, AZ, BY, KG, KZ, MD, RU, TJ, TM, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR, BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG				
	EP 1689816	A1	20060816	EP 2004-799609	20041104
	R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, SI, FI, RO, CY, TR, BG, CZ, EE, HU, PL, SK, IS				
	CN 1875071	A	20061206	CN 2004-80032282	20041104
	US 2007225437	A1	20070927	US 2004-578798	20041104
	JP 2005154766	A	20050616	JP 2004-322805	20041105
	KR 2007007255	A	20070115	KR 2006-711172	20060607
PRAI	JP 2003-378521	A	20031107		
	WO 2004-JP16716	W	20041104		

AB A curable silicone composition with accelerated curability producing cured sealant/adhesive for electronics with high flexibility, improved adhesion and excellent elec. properties includes three parts: A, B, C. A is an organopolysiloxane represented by the siloxane unit formula: [R13SiO1/2]a [R22SiO2/2]b [R3SiO3/2]c, where R1, R2, and R3 are univalent organic groups, ≥2 of which are univalent organic groups which contain epoxy groups and are free of aromatic rings and > 20 mol % of R3 are aryl groups and where a + b + c = 1; and where $0 \leq a \leq 0.8$; $0 \leq b \leq 0.8$; $0.2 \leq c \leq 1.0$. B is a linear chain organopolysiloxane having ≥ 2 univalent organic groups that contain phenolic hydroxyl groups. C is a curing accelerator and can be exemplified by amines, organometallic compds., organophosphorus compds., organic ammonium or

sulfonium salts, boron complex compds. and organic peroxides. Under the effect of curing accelerator the epoxy group of component A reacts with the phenolic hydroxyls of component B, thus providing crosslinking and curing.

IT 851539-16-7
RL: POF (Polymer in formulation); PRP (Properties); TEM (Technical or engineered material use); USES (Uses)
(component B; tri-component curable silicone composition with accelerated curability as sealant/adhesive for electronics with high flexibility and improved adhesion characteristics)

RN 851539-16-7 HCAPLUS
CN Phenol, 3,3'-[(1,1,3,3-tetramethyl-1,3-disiloxanediyl)di-3,1-propanediyl]bis- (9CI) (CA INDEX NAME)



RETABLE

Referenced Author (RAU)	Year (RPY)	VOL (RVL)	PG (RPG)	Referenced Work (RWK)	Referenced File
Anon	1995	1995		PATENT ABSTRACTS OF	
Dow Corning Toray Silic	1993			EP 0571965 A	HCAPLUS
Morita	1996			US 5516858 A	HCAPLUS
Shin Etsu Chem Co Ltd	1994			JP 06306084 A	HCAPLUS

L33 ANSWER 3 OF 5 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 1994:193643 HCAPLUS Full-text
DN 120:193643
TI Aromatic cyanate-siloxane curable compositions
IN Liao, Zeng K.; Wang, Chun S.
PA Dow Chemical Co., USA
SO U.S., 14 pp. Cont. of U.S. Ser. No. 505,310, abandoned.
CODEN: USXXAM
DT Patent
LA English
FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	US 5260398	A	19931109	US 1992-837464	19920214
	US 5300591	A	19940405	US 1993-93497	19930716
	US 5326893	A	19940705	US 1993-147279	19931027
PRAI	US 1990-505310	B2	19900405		
	US 1992-837464	A3	19920214		
	US 1993-93497	A3	19930716		

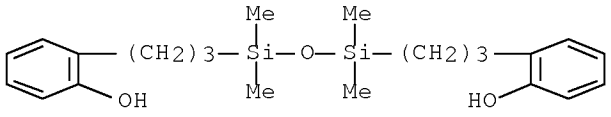
AB The title compns., useful for adhesives, coatings, laminates, composites, encapsulants, etc., comprise ≥1 compound containing ≥1 vicinal aromatic cyanate/mol. and ≥1 of the compound having ≥1 organosiloxane/mol. and ≥1 curing catalyst. Stirring 0.5 mol 2-allylphenol in PhMe solution in 0.25 mol 1,1,3,3-tetramethyldisiloxane in PhMe solution at 75° with H2PtCl6 and tert-amyl alc. and heating to 105° gave brown color and purity ≥92% 1,3-bis(3'-(2-hydroxyphenyl)propyl)-1,1,3,3-tetramethyldisiloxane, 0.1 mol of which was reacted with 0.24 mol CNBr in methylene chloride at -30° and 0.26 mol NEt3, and hydrolyzed to give 1,3-bis(3'-(2-cyanatophenyl)propyl)- 1,1,3,3-tetramethyldisiloxane (I). A curable composition was prepared from I, a

functional (2.2) dicyclopentadiene-phenol copolymer cyanate ester having cyanate equivalent weight 213, and Co acetylacetonate.

IT 4515-51-9P
RL: RCT (Reactant); SPN (Synthetic preparation); PREP (Preparation); RACT (Reactant or reagent)
(preparation and reaction of, for curable cyanato siloxane compns.)

RN 4515-51-9 HCAPLUS

CN Phenol, 2,2'-[(1,1,3,3-tetramethyl-1,3-disiloxanediyl)di-3,1-propanediyl]bis- (9CI) (CA INDEX NAME)



L33 ANSWER 4 OF 5 HCAPLUS COPYRIGHT 2008 ACS on STN

AN 1994:9729 HCAPLUS Full-text

DN 120:9729

TI Novel aromatic organosiloxanes containing hydroxy groups and their use for thermally stable epoxy resins and cured products

IN Liao, Zeng K.; Wang, Chun S.

PA Dow Chemical Co., USA

SO U.S., 33 pp. Cont.-in-part of U.S. Ser. No. 439,208, abandoned.
CODEN: USXXAM

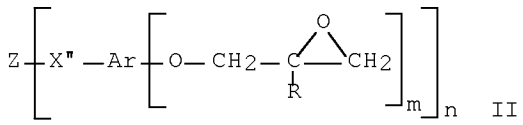
DT Patent

LA English

FAN.CNT 1

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI US 5206312	A	19930427	US 1991-729508	19910712
PRAI US 1989-439208	B2	19891120		

GI



II

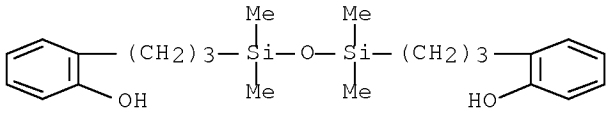
AB The title resins having improved moisture resistance, elec. properties, and low stress, useful for electronic applications, coatings, and composites, are made by reacting (1) ≥1 compound containing an average of >1 aromatic HO group with (2) ≥1 compound containing an average of >1 vicinal epoxy group per mol. provided that ≥1 component of (2) is a siloxane (oligomer) containing aromatic OH groups Z[X''Ar(OH)m]n [I; Ar = (un)substituted di- or multivalent aromatic group; X'' = C2-12 (cyclo)alkylene, C2-12 (cyclo)alkoxyalkylene; Z = n-valent entity containing >1 organosiloxane moiety; m = 1-3; n = 1-200] or II (R = H, C1-3 alkyl; Ar, Z, m, n as defined for I). Thus, a composition containing 1,1,1-tris(4-hydroxyphenyl)methane triglycidyl ether (ERL-4221) 5, 1,3-bis[3-(2-hydroxyphenyl)-propyl]- 1,1,3,3-tetramethyldisiloxane (preparation by

hydrosilylation of 2-allylphenol with 1,1,3,3-tetramethyldisiloxane given) 0.5, hexahydrophthalic anhydride (curing agent) 10.8, and 2-ethyl-4-methylimidazole (catalyst) 0.06 g was cured 1 h at 130°, 2 h at 180°, and 2 h at 230° to give a casting having glass temperature 198° (DSC).

IT 4515-51-9DP, polymers with epoxy cresol novolac resins
RL: PREP (Preparation)
(preparation of, with high thermal stability)

RN 4515-51-9 HCAPLUS

CN Phenol, 2,2'-[(1,1,3,3-tetramethyl-1,3-disiloxanediyl)di-3,1-propanediyl]bis- (9CI) (CA INDEX NAME)



L33 ANSWER 5 OF 5 HCAPLUS COPYRIGHT 2008 ACS on STN

AN 1966:11621 HCAPLUS Full-text

DN 64:11621

OREF 64:2127a-c

TI Silylalkylphenols

IN Plueddemann, Edwin P.

PA Dow Corning Corp.

SO 18 pp.

DT Patent

LA Unavailable

FAN.CNT 1

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI FR 1387338		19650129	FR 1963-958149	19631223
DE 1221222			DE	
GB 1022742			GB	
PRAI US		19630109		

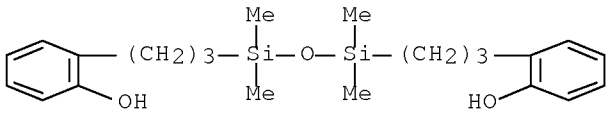
GI For diagram(s), see printed CA Issue.

AB Unlike silylphenols, the title compds. are stable to hydrolysis. A mixture of 67 g. o-allylphenol, 70 g. C6H6, and 0.2 g. 0.3% H2PtCl6 solution in MeOCH2CH2OMe was refluxed at 95-100°, and 135 g. HSiCl3 added slowly, causing the temperature to rise to 110° within 1 hr. Distillation of the mixture yielded 30 g. I, hydrolysis of which gave 2- HOC6H4CH2CH2CH2SiO1.5. Similarly were prepared Me3SiOSiMe2CH2CH2CH2C6H3(OMe)(OH)-3,4, b0.2 120°, d25 0.973, and n25D 1.6805, [4,3-(HO)(MeO)C6H3CH2CH2CH2SiMe2]2O, b0.2 215°, d25 1.042, Me3SiOSiMe2CHMeCH2C6H3(OMe)(OH)-3,4, b0.5 130-5°, n25D 1.4810, d. 0.973, [4,3-(HO)(MeO)C6H3CH2CHMeSiMe2]2O, b0.2 218-30°, n25D 1.5078, d. 1.035, Me3SiOSiMe2CH2CH2CH2C6H4OH-2, b0.5 115.8°, n25D 1.4791, [2-HOC6H4CH2CH2CH2SiMe2]2O, b1 213-15°, n25D 1.5216, d25 1.034, II, b1 80°, 3-Me3SiOSiMe2C15H30C6H4OH, b0.5 190-5°, d. 0.916, CH2:CHCH2C6H3(OSiMe3)(OMe)-4,3, b0.1 75-80°, n25D 1.4958, (MeO)3SiCH2CH2CH2C6H3(SiMe3)(OMe)-4,3, b0.4 158-67°; n25D 1.4745, III. The silylalkylphenols are useful as plasticizers for phenolic resins, as curing agents for epoxy resins, and as coatings for glass fibers used in reinforced polyester resins.

IT 4515-51-9P, Phenol, 2,2'-[(tetramethyldisiloxanylene)bis(trimethylene)]di-
RL: PREP (Preparation)
(preparation of)

RN 4515-51-9 HCAPLUS

CN Phenol, 2,2'-[(1,1,3,3-tetramethyl-1,3-disiloxanediyl)di-3,1-propanediyl]bis- (9CI) (CA INDEX NAME)

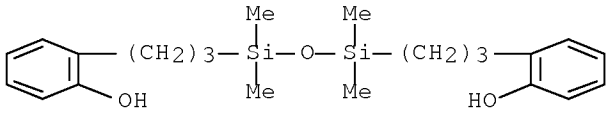


=> d bib abs hitstr retable tot l34

L34 ANSWER 1 OF 10 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 2003:396871 HCAPLUS Full-text
DN 138:402371
TI Benzoxazines having polymerizable side groups, thermosetting resins, and uses
IN Dershem, Stephen M.; Liu, Puwei; Mizori, Farhad
PA Henkel Loctite Corporation, USA
SO PCT Int. Appl., 43 pp.
CODEN: PIXXD2
DT Patent
LA English
FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	WO 2003042196	A1	20030522	WO 2002-US35987	20021108 <--
	W: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NO, NZ, OM, PH, PL, PT, RO, RU, SC, SD, SE, SG, SI, SK, SL, TJ, TM, TN, TR, TT, TZ, UA, UG, UZ, VC, VN, YU, ZA, ZM, ZW				
	RW: GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW, AM, AZ, BY, KG, KZ, MD, RU, TJ, TM, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, SK, TR, BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG				
	US 2003125551	A1	20030703	US 2001-8591	20011113 <--
	US 6743852	B2	20040601		
	AU 2002363640	A1	20030526	AU 2002-363640	20021108 <--
	US 2004123948	A1	20040701	US 2003-735119	20031211 <--
PRAI	US 2001-8591	A	20011113 <--		
	WO 2002-US35987	W	20021108 <--		

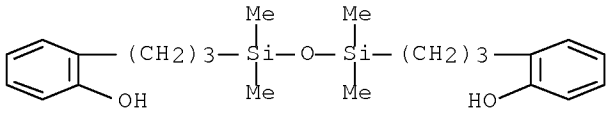
OS MARPAT 138:402371
AB The polymers are particularly useful for increasing adhesion at interfaces within microelectronic packages (die-attach pastes), and have low shrinkage on cure and low coefficient of thermal expansion (CTE). Thus, hydroquinone, 3-amino-1-propanol vinyl ether, HCOH are reacted to give a divinyl ether benzoxazine, that when added (8%) to a thermosetting bismaleimide resin adhesive showed 290% adhesion enhancement (based on tensile values).
IT 4515-51-9P
RL: IMF (Industrial manufacture); RCT (Reactant); PREP (Preparation); RACT (Reactant or reagent)
(intermediate; for polymerizable benzoxazines for adhesives)
RN 4515-51-9 HCAPLUS
CN Phenol, 2,2'-[(1,1,3,3-tetramethyl-1,3-disiloxanediyl)di-3,1-propanediyl]bis- (9CI) (CA INDEX NAME)



RETABLE

Referenced Author (RAU)	Year (RPY)	VOL (RVL)	PG (RPG)	Referenced Work (RWK)	Referenced File
Anon	1995	1995		PATENT ABSTRACTS OF	
Anon	1998	1998		PATENT ABSTRACTS OF	
Chirachanchai, S	2001	8	355	COMPOSITE INTERFACES	HCAPLUS
Ciba Ag	1970			DE 2018625 A	HCAPLUS
Dershem, S	2000			US 6034195 A	HCAPLUS
Edison Polymer Innovati	1999			WO 9918092 A	HCAPLUS
Edison Polymer Innovati	2000			WO 0027921 A	HCAPLUS
Edison Polymer Innovati	2000			WO 0061650 A	HCAPLUS
Fields, D	1962	27	2749	JOURNAL OF ORGANIC C	HCAPLUS
Hitachi Chem Co Ltd	1994			JP 06345898 A	HCAPLUS
Hitachi Chem Co Ltd	1998			JP 10259248 A	HCAPLUS
Ishida, H	1996			US 5543516 A	HCAPLUS
Ishida, H	1998	69	2559	JOURNAL OF APPLIED P	HCAPLUS
Monsanto Co	1985			EP 0147382 A	HCAPLUS
Pei, D	1998		595	GAOFENZI XUEBAO	HCAPLUS

L34 ANSWER 2 OF 10 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 2001:909565 HCAPLUS Full-text
DN 136:184218
TI Oligodimethylsiloxane linked cyanate ester resins
AU Maya, Eva M.; Snow, Arthur W.; Buckley, Leonard J.
CS U.S. Naval Research Laboratory, Washington, DC, 20375, USA
SO Macromolecules (2002), 35(2), 460-466
CODEN: MAMOBX; ISSN: 0024-9297
PB American Chemical Society
DT Journal
LA English
AB A series of dimethylsiloxane linked cyanate ester monomers, NCOC6H4(CH2)3(Si(CH3)2O)nSi(CH2)3C6H4OCN, where n = 1, 2, 3, were synthesized and characterized. Monomers had m.ps. in the range from 5 to -12°, and characterization included 1H, 13C NMR, IR spectroscopy and DSC. Thermoset formation occurred by cyclotrimerization of the cyanate group to cyanurate structure. Cured resins were homogeneous rubbery castings with Tg ranging from 15 to -43°. Dielec. consts. showed little dependence on siloxane chain length and strong dependence on frequency (2.5/15 GHz and 2.85/1 GHz). The corresponding loss tangent increased with siloxane chain length and showed small frequency dependence.
IT 4515-51-9P
RL: PRP (Properties); RCT (Reactant); SPN (Synthetic preparation); PREP (Preparation); RACT (Reactant or reagent)
(in synthesis of cyanurate-linked polydimethylsiloxanes)
RN 4515-51-9 HCAPLUS
CN Phenol, 2,2'-[(1,1,3,3-tetramethyl-1,3-disiloxanediyl)di-3,1-propanediyl]bis- (9CI) (CA INDEX NAME)



RETABLE

Referenced Author (RAU)	Year (RPY)	VOL (RVL)	PG (RPG)	Referenced Work (RWK)	Referenced File
Arnold, C	1992	37	128	37th Int SAMPE Symp	HCAPLUS
Beevers, M	1983	24	1565	Polymer	HCAPLUS
Beevers, M	1993		415	Siloxane Polymers, C	
Bondi, A	1968			Physical Properties	
Cozzens, R	1987	34	601	J Appl Polym Sci	HCAPLUS
Dasgupta, S	1967	47	2911	J Chem Phys	HCAPLUS
Delano, C	1975	20	243	20th Nat SAMPE Symp	HCAPLUS
Dudeck, K	1992	41	723	IEEE Trans Instrum M	HCAPLUS
Eaborn, C	1992	198-2	337	Inorg Chim Acta	HCAPLUS
Fang, T	1995		61	Progress in Polymer	HCAPLUS
Grigat, E	1964	97	3012	Chem Ber	HCAPLUS
Hergenrother, P	1978	23	506	23rd Nat SAMPE Symp	HCAPLUS
Kohler, H	1987	27	294	Z Chem	
Lee, W	1975		III	Polymer Handbook	HCAPLUS
Liao, S	1973	59	3825	J Chem Phys	HCAPLUS
Liao, Z	1993			US 5260398	HCAPLUS
Martin, D	1967	7	123	Z Chem	HCAPLUS
Mathias, L	1993	26	4070	Macromolecules	HCAPLUS
Mumby, S	1989	18	241	J Electron Mater	HCAPLUS
Naoki, M	1983	24	1145	Polymer	
Nicolson, A	1970	19	377	IEEE Trans Instrum M	
Pankratov, V	1977	46	278	Russ Chem Rev	
Pollack, S	1998	39	452	Polym Prepr	HCAPLUS
Reich, P	1965	98	2063	Chem Ber	HCAPLUS
Shimp, D	1989			US 4847233	HCAPLUS
Shimp, D	1986	54	107	Am Chem Soc:Polym Ma	HCAPLUS
Shimp, D	1994		230	Chemistry and Techno	HCAPLUS
Snow, A	1994		7	Chemistry and Techno	HCAPLUS
Snow, A	1999	1	189	Handbook of Low and	HCAPLUS
Snow, A	1999	37	135	J Polym Sci, Part A:	HCAPLUS
Snow, A	1997	30	394	Macromolecules	HCAPLUS
Warrick, E	1952	44	2196	Ind Eng Chem	HCAPLUS

L34 ANSWER 3 OF 10 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 1977:585014 HCAPLUS Full-text
DN 87:185014
OREF 87:29241a,29244a
TI Preparation of silicon-containing polycarbonates by low-temperature polycondensation in an organic medium
AU Sheludyakov, V. D.; Gorlov, E. G.; Mkhitaryan, S. S.; Zhinkin, D. Ya.
CS USSR
SO Vysokomolekulyarnye Soedineniya, Seriya B: Kratkie Soobshcheniya (1977), 19(9), 659-63
CODEN: VYSBAI; ISSN: 0507-5483
DT Journal
LA Russian
AB The title polycarbonates were obtained by polycondensation of diols (HOCH2SiMe2)2O (I), [HO(CH2)3SiMe2]2O (II), and [o-HOC6H4(CH2)3SiMe2]2O (III) with phosgene, and by polycondensation of bis-chloroformates of I-III with

bisphenol A, as well as by copolycondensation of I or III with bisphenol A and phosgene. The reactions were conducted in organic solvents (PhMe, CH2Cl2, CCl4, etc.) in the presence of Et3N or pyridine. Optimum conditions of the reactions with resp. to reduced viscosity and yield of the polymers were established, and physicomech. properties (solubility, glass transition temperature, etc.) and thermal stabilities of the latter were determined

IT 60338-33-2P
RL: SPN (Synthetic preparation); PREP (Preparation)
(preparation, physicomech. properties and thermal stability of)

RN 60338-33-2 HCAPLUS

CN Carbonic dichloride, polymer with 2,2'-[(1,1,3,3-tetramethyl-1,3-disiloxanediyl)di-3,1-propanediyl]bis[phenol] (9CI) (CA INDEX NAME)

CM 1

CRN 4515-51-9
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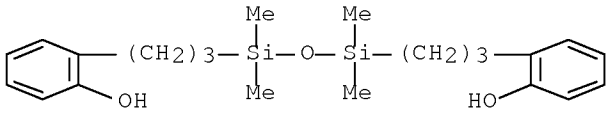

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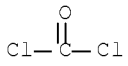


L34 ANSWER 4 OF 10 HCAPLUS COPYRIGHT 2008 ACS on STN

AN 1976:509031 HCAPLUS Full-text

DN 85:109031

OREF 85:17520h,17521a

TI Study of the interfacial polycondensation of disiloxane series diols with phosgene

AU Sheludyakov, V. D.; Mkhitaryan, S. S.; Gorlov, E. G.; Zhinkin, D. Ya.

CS USSR

SO Vysokomolekulyarnye Soedineniya, Seriya A (1976), 18(7), 1545-8
CODEN: VYSAAF; ISSN: 0507-5475

DT Journal

LA Russian

AB 1,3-Bis(hydroxymethyl)-1,1,3,3-tetramethyldisiloxane-phosgene copolymer (I) [60338-31-0], 1,3-bis(γ-hydroxypropyl)-1,1,3,3- tetramethyldisiloxane-phosgene copolymer (II) [60338-32-1], and 1,3-bis[γ-(o-hydroxyphenyl)propyl]-1,1,3,3-tetramethyldisiloxane- phosgene copolymer (III) [60338-33-2] of number-average mol. wts. 1000-5000 were prepared by interfacial polymerization of the resp. disiloxanediols with Cl2CO. Relatively low mol. wts. and low yields (23.1-38.4, 22.8-32.6, and 63.0-86.1% for I, II, and III, resp.) were ascribed to low reactivities of the OH groups resulting in side reactions of Cl2CO,

hydrolysis and cleavage of the siloxane bonds. I-III were stable in air up to 250-300°.

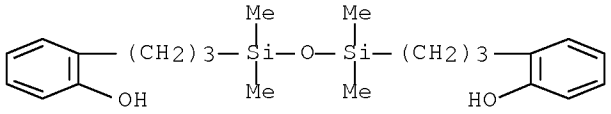
IT 60338-33-2P
RL: SPN (Synthetic preparation); PREP (Preparation)
(preparation, structure and thermal stability of)

RN 60338-33-2 HCAPLUS

CN Carbonic dichloride, polymer with 2,2'-[(1,1,3,3-tetramethyl-1,3-disiloxanediyl)di-3,1-propanediyl]bis[phenol] (9CI) (CA INDEX NAME)

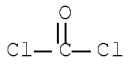
CM 1

CRN 4515-51-9
CMF C22 H34 O3 Si2



CM 2

CRN 75-44-5
CMF C Cl2 O



L34 ANSWER 5 OF 10 HCAPLUS COPYRIGHT 2008 ACS on STN

AN 1975:17156 HCAPLUS Full-text

DN 82:17156

OREF 82:2763a,2766a

TI Interaction of organosilicon bis(chloroformates) with amines and hydrazine

AU Gol'din, G. S.; Baturina, L. S.; Sheludyakov, V. D.; Khatuntsev, G. D.

CS Gos. Nauchno-Issled. Inst. Khim. Tekhnol. Elementoorg. Soedin., USSR

SO Sintez i Fiziko-Khimiya Polimerov (1974), 13, 33-40
CODEN: SFKPAO; ISSN: 0583-4317

DT Journal

LA Russian

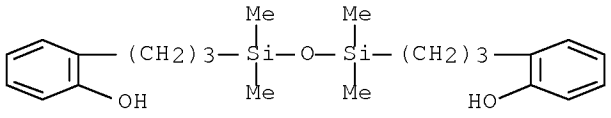
AB Chloroformylated disiloxanes, 1,3-bis[(chloroformoxy)methyl]-1,1,3,3-tetramethyldisiloxane [20566-53-4], and its bis[γ- chloroformyloxy)propyl], bis[[β-(chloroformyloxy)ethoxy]methyl], and bis[γ-[ω-(chlorofomyloxy)phenyl]propyl] analogs were prepared by reacting the corresponding diols with phosgene [75-44-5]. Their condensation with sec. diamines, e.g. N,N'-dimethyl-1,2-ethanediamine [110-70-3] or N,N'-dimethyl-N-[2-(methylamino)ethyl]-1,2-ethanediamine [105-84-0], or with trimethylsilyl-containing polyamines, e.g., N,N'-dimethyl-N,N'-bis(trimethylsilyl)-1,2-ethanediamine [1821-97-2], or with hydrazine [302-01-2] gave the corresponding copolymers. Ten copolymers of this type, e.g. 1,3-bis[(chloroformyloxy)methyl]-1,1,3,3- tetramethyldisiloxane-N,N'-dimethyl-1,2-ethanediamine copolymer [53049-47-1] or 1,3-bis[γ-(o-

(chloroformyloxy)phenyl]propyl]-1,1,3,3- tetramethyldisiloxane-hydrazine copolymer [53049-61-9] were prepared

IT 4515-51-9
RL: RCT (Reactant); RACT (Reactant or reagent)
(reaction of, with phosgene)

RN 4515-51-9 HCAPLUS

CN Phenol, 2,2'-[(1,1,3,3-tetramethyl-1,3-disiloxanediyl)di-3,1-propanediyl]bis- (9CI) (CA INDEX NAME)



L34 ANSWER 6 OF 10 HCAPLUS COPYRIGHT 2008 ACS on STN

AN 1973:442603 HCAPLUS Full-text

DN 79:42603

OREF 79:6933a,6936a

TI Reaction of organosilicon alcohols and phenols with phosgene

AU Mironov, V. F.; Sheludyakov, V. D.; Khatuntsev, G. D.; Kozlikov, V. L.

CS USSR

SO Zhurnal Obshchei Khimii (1973), 43(3), 616-20
CODEN: ZOKHA4; ISSN: 0044-460X

DT Journal

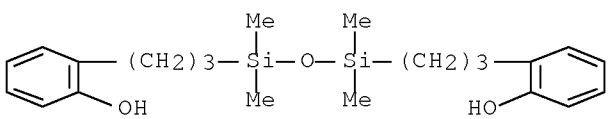
LA Russian

AB $COCl_2$ reacted at 0-10° with $O(SiMe_2ZOH)_2$ (I; Z = CH_2, $(CH_2)_3$, $CH_2OCH_2CH_2$) to form $O(SiMe_2ZO_2CCl)_2$ (II), $SiMe_2(ZCl)Cl$ (III), and $ClSiMe_2ZO_2CCl$ (IV); the ratios were controlled by reactant ratios and the nature of Z. Thus, passing $COCl_2$ into $O(SiMe_2CH_2OH)_2$ in THF gave mainly 94% II (Z = CH_2) also formed in similar yield from liquid $COCl_2$ if the resulting HCl was removed; III was the only by-product. The yield of III was enhanced by residual HCl. I(Z = $CH_2OCH_2CH_2$) gave IV besides the predominantly formed disiloxane, but minor amts. of $ClSiMe_2CH_2Cl$, $(CH_2O_2CCl)_2$, $ClCO_2CH_2CH_2Cl$ and $(CH_2Cl)_2$ were also found. The Si-containing phenols were inert towards $COCl_2$ at moderate-temps. but with added Et_3N gave $HSiMe_2C_6H_4O_2CCl$ (m- and p-isomers). Similarly were prepared (o-$ClCO_2C_6H_4SiMe_2)_2O$ and (o-$ClCO_2C_6H_4OCH_2SiMe_2)_2O$, which with the appropriate phenols and Et_3N gave $(HSiMe_2C_6H_4O)_2CO$ (o- and p-isomers).

IT 4515-51-9
RL: RCT (Reactant); RACT (Reactant or reagent)
(reaction with phosgene)

RN 4515-51-9 HCAPLUS

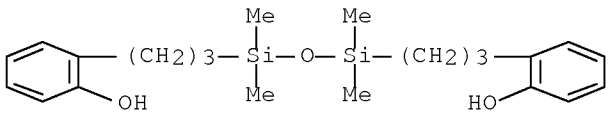
CN Phenol, 2,2'-[(1,1,3,3-tetramethyl-1,3-disiloxanediyl)di-3,1-propanediyl]bis- (9CI) (CA INDEX NAME)



L34 ANSWER 7 OF 10 HCAPLUS COPYRIGHT 2008 ACS on STN

AN 1972:153842 HCAPLUS Full-text

DN 76:153842
OREF 76:25081a,25084a
TI Chemical transformations of compounds obtained from alkenoxydiorganosilanes by hydrosilylation
AU Mironov, V. F.; Kozlikov, V. L.; Kozyukov, V. P.; Fedotov, N. S.; Khatuntsev, G. D.; Sheludyakov, V. D.
CS USSR
SO Zhurnal Obshchei Khimii (1971), 41(11), 2470-5
CODEN: ZOKHA4; ISSN: 0044-460X
DT Journal
LA Russian
AB Addg. 58 g CH2:CHCH2OH over 1 hr to 94.6 g Me2SiHCl and 66 g urea and warming to 65° gave 95% Me2SiH(OCH2CH:CH2) which with H2PtCl6 catalyst polymerized in an exothermic reaction, having been heated gradually during mixing, and gave a polymer with mol. weight .apprx.1000. This in 20% NaOH in 5 hr heating gave O(SiMe2CH2CH2CH2OH)2 (I). Heating the polymer with AlCl3 gave 89% Me2SiCl2 while reaction of the polymer with SOCl2 in a stream of dry HCl gave 75% Me2SiCl(CH2)3Cl. The polymer treated with COCl2 in the presence of ZnCl2 at 110-30° gave ClSiMe2CH2CH2CH2O2CCl (II), also formed by similar treatment of the depolymn. products obtained by heating the polymer to 280-350°; the same product also formed from 1,1-dimethyl-1-sila-2-oxocyclopentane and COCl2 in the presence of AlCl3. Similarly were prepared ClSiMe2-(CH2)4O2CCl, and ClSiMe2CH2CHMe(CH2)2O2CCl. COCl2 and HCl passed at 130° into 2,2-dimethyl-1-oxa-2-sila-6,7-phenylene-cycloheptane gave 80% ClSiMe2(CH2)3C6H4O2CCl-o. I and COCl2 gave 72% O[SiMe2CH2CH2CH2O2CCl)2 and 20% II. O[SiMe2(CH2)3C6H4OH-o]2 and COCl2 in the presence of Et3N at -20° gave 80% O[SiMe2(CH2)3C6H4O2CCl]2. I treated with solid NaOH gave 69% 2,2-dimethylsila-1-oxacyclopentane and 31% 2,2,4,4-tetramethyl-2,4-disila- 1,3-dioxacycloheptane; the latter with dilute HCl 3 hr gave O(SiMe2OSiMe2CH2CH2CH2OH)2.
IT 4515-51-9P
RL: SPN (Synthetic preparation); PREP (Preparation)
(preparation of)
RN 4515-51-9 HCAPLUS
CN Phenol, 2,2'-[(1,1,3,3-tetramethyl-1,3-disiloxanediyl)di-3,1-propanediyl]bis- (9CI) (CA INDEX NAME)



L34 ANSWER 8 OF 10 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 1972:46295 HCAPLUS Full-text
DN 76:46295
OREF 76:7469a,7472a
TI Bis[hydroxyalkyl(cor aryl)]tetraorganodisiloxanes
IN Mironov, V. F.; Kozlikov, V. L.
SO U.S., 4 pp.
CODEN: USXXAM
DT Patent
LA English
FAN.CNT 3

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE

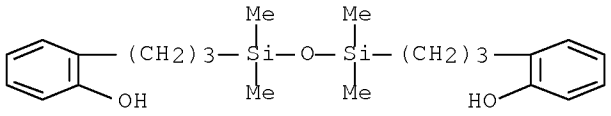
PI	US 3622609	A	19711123	US 1968-754449	19680821 <--
	SU 251577	A1	19760725	SU 1967-1182274	19670823 <--
PRAI	SU 1967-1182274	A	19670823 <--		

AB The title compds. (HORSiMe2)2O (I, R=saturated or unsatd. alkylene or aralkylene) were prepared by treating Me2SiClH with unsatd. alcs. in the presence of PhNMe2 followed by polymerization of the resultant alkenyloxysilanes and alkaline hydrolysis. Thus, allyl alc. was added to an equimol. mixture Me2SiClH and PhNMe2 in Bu2O to give allyloxydimethylsilane, which was heated with 0.1N H2PtCl6 in iso-PrOH to yield a mixture of siloxyalkanes. The mixture was boiled with 20% aqueous NaOH to give I [R=(CH2)3]. Similarly prepared were I [R=CH2CHMeCH2, o-C6H4(CH2)3, and CH2CH:CH].

IT 4515-51-9P
RL: SPN (Synthetic preparation); PREP (Preparation)
(preparation of)

RN 4515-51-9 HCAPLUS

CN Phenol, 2,2'-[(1,1,3,3-tetramethyl-1,3-disiloxanediyl)di-3,1-propanediyl]bis- (9CI) (CA INDEX NAME)



L34 ANSWER 9 OF 10 HCAPLUS COPYRIGHT 2008 ACS on STN

AN 1972:4464 HCAPLUS Full-text

DN 76:4464

OREF 76:781a,784a

TI 1,3-Bis[hydroxyalkyl- or -aralkyl]tetraorganodisiloxanes used as antifoams and pore size regulators

IN Mironov, V. F.; Kozlikov, V. L.

SO Brit., 6 pp.
CODEN: BRXXAA

DT Patent

LA English

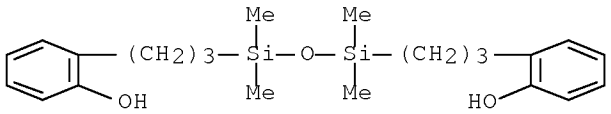
FAN.CNT 3

PI	GB 1243024	A	19710818	GB 1968-1243024	19680823 <--
	SU 251577	A1	19760725	SU 1967-1182274	19670823 <--
PRAI	SU 1967-1182274	A	19670823 <--		

AB 1,3-Bis(hydroxyalkyl- or hydroxyaralkyl)tetramethyldisiloxanes (I, R = (CH2)3, CH2CH(Me)CH2, o-C6H4(CH2)3, CH2CH:CH2), useful as antifoams, pore size regulators, and monomers, were prepared by treating Me2Si(Cl)H with an alc. or phenol in the presence of a base, polymerizing the alkyloxysilane to II with an iso-PrOH solution of chloroplatinic acid (III), and hydrolyzing II with aqueous NaOH. For example, allyl alc. was added during 4 hr to a mixture of Bu2O, Me2Si(Cl)H, and PhNMe2, the mixture was stirred 8 hr, and allowed to stand 12 hr to give 86% Me2Si(OCH2CH:CH2)H, 10 ml of which was heated to 120.deg. with 2 drops 0.1M III in iso-PrOH, and the remainder of a total of 1,405 g Me2Si(OCH2CH:CH2)H was added while heating to 185-210.deg., giving 1,405 g II. A mixture of 77 g polymer and 100 ml 20% NaOH was refluxed 5 hr, cooled, and treated with 2 100 ml portions 10% H2SO4 to give 95% 1,3-bis(3-hydroxypropyl)-1,1,3,3,-tetramethyldisiloxane [18001-97-3]. Similarly, 3 other I were prepared

IT 4515-51-9

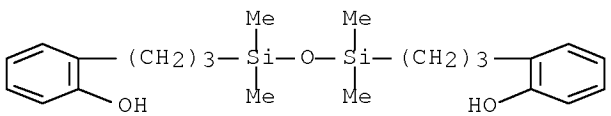
RL: USES (Uses)
(antifoaming agents)
RN 4515-51-9 HCAPLUS
CN Phenol, 2,2'-[(1,1,3,3-tetramethyl-1,3-disiloxanediyl)di-3,1-propanediyl]bis- (9CI) (CA INDEX NAME)



L34 ANSWER 10 OF 10 HCAPLUS COPYRIGHT 2008 ACS on STN
AN 1971:76521 HCAPLUS Full-text
DN 74:76521
OREF 74:12423a,12426a
TI 1,3-Bis(Hydroxyalkyl or -aryl)tetraorganodisiloxanes
IN Mironov, V. F.; Kozlikov, V. L.
SO Fr., 8 pp.
CODEN: FRXXAK
DT Patent
LA French
FAN.CNT 1

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI FR 1598951		19700821	FR	19680828 <--

AB The title compds. which can be used in the preparation of polycarbonates, polyurethanes, polyesters, epoxy resins, and antifoaming agents, are prepared in improved yields by treating diorganohalosilanes with unsatd. alcs. in the presence of an amine as acid acceptor, polymerizing the alkenyl-oxydiorganosilanes in the presence of H2PtCl6, and treating the silaoxaalkanes with NaOH. As an example, a mixture of HSiMe2Cl, PhNMe2, and allyl alc. in Bu2O was stirred at ambient temperature, the HSiMe2OCH2CH:CH2 formed was polymerized in the presence of H2PtCl6, and the product boiled with 20% NaOH to give 98% 1,3-bis(3-hydroxypropyl)-1,1,3,3-tetramethyldisilox- ane. Methallyl alc., o-allylphenol, and propargyl alc. were also used instead of allyl alc. Also prepared were 1,3-bis(2-methyl-3-hydroxypropyl)- 1,1,3,3,-tetramethyldisiloxane, 1,3-bis-[γ-(o-hydroxyphenyl)propyl]- 1,1,3,3-tetramethyldisiloxane, and 1,3-bis(3-hydroxy-2-propenyl)-1,1,3,3-tetramethyldisiloxane.
IT 4515-51-9P
RL: SPN (Synthetic preparation); PREP (Preparation)
(preparation of)
RN 4515-51-9 HCAPLUS
CN Phenol, 2,2'-[(1,1,3,3-tetramethyl-1,3-disiloxanediyl)di-3,1-propanediyl]bis- (9CI) (CA INDEX NAME)



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L4             4 SEA FILE=REGISTRY ABB=ON  PLU=ON  L3 NOT PHENOL
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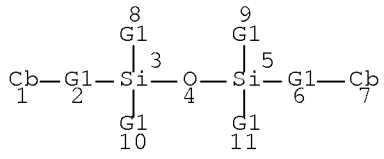


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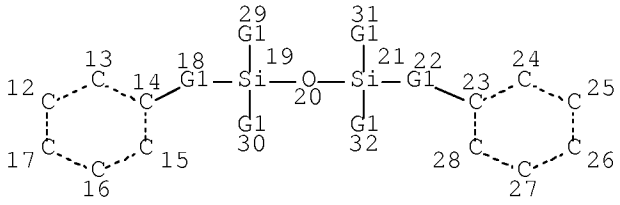

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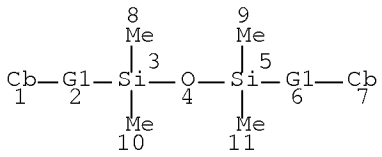

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STEREO ATTRIBUTES: NONE
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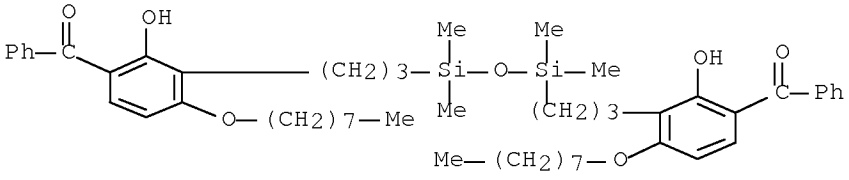
L48 52 ANSWERS REGISTRY COPYRIGHT 2008 ACS on STN
IN Methanone, [(1,1,3,3-tetramethyl-1,3-disiloxanediyl)bis[3,1-propanediyl[2-hydroxy-4-(octyloxy)-3,1-phenylene]]]bis[phenyl- (9CI)
MF C52 H74 O7 Si2

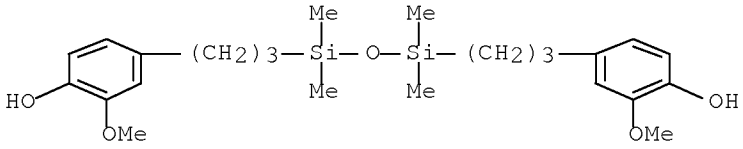


PROPERTY DATA AVAILABLE IN THE 'PROP' FORMAT

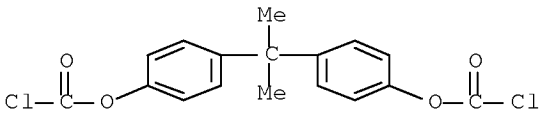
HOW MANY MORE ANSWERS DO YOU WISH TO SCAN? (1):10

L48 52 ANSWERS REGISTRY COPYRIGHT 2008 ACS on STN
IN Carbonochloridic acid, (1-methylethylidene)di-4,1-phenylene ester, polymer with 4,4'-(1-methylethylidene)bis[phenol] and 4,4'-[(1,1,3,3-tetramethyl-1,3-disiloxanediyl)di-3,1-propanediyl]bis[2-methoxyphenol] (9CI)
MF (C24 H38 O5 Si2 . C17 H14 Cl2 O4 . C15 H16 O2)x
CI PMS

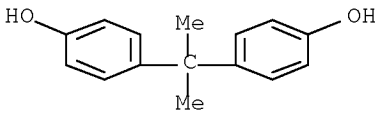
CM 1



CM 2



CM 3



L48 52 ANSWERS REGISTRY COPYRIGHT 2008 ACS on STN
IN Disiloxane, 1,3-bis[3-[3,5-dimethyl-4-(oxiranylmethoxy)phenyl]propyl]-1,1,3,3-tetramethyl- (9CI)

MF C32 H50 O5 Si2
CI COM

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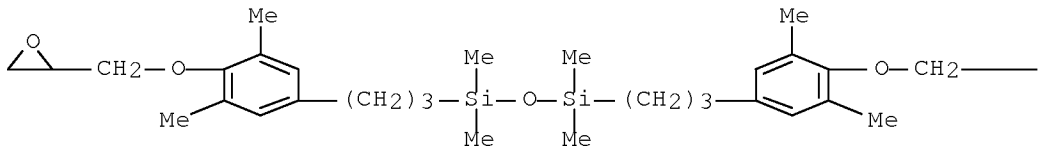
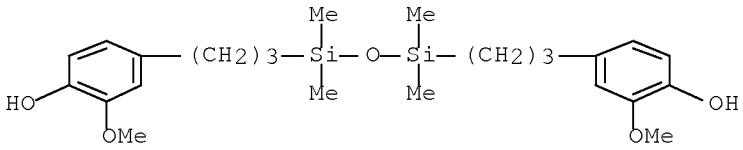


PAGE 1-B

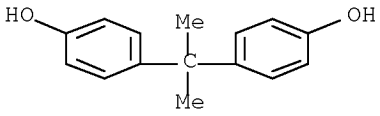
PROPERTY DATA AVAILABLE IN THE 'PROP' FORMAT

L48 52 ANSWERS REGISTRY COPYRIGHT 2008 ACS on STN
IN Carbonic dichloride, polymer with 4,4'-(1-methylethylidene)bis[phenol] and 4,4'-[(1,1,3,3-tetramethyl-1,3-disiloxanediyl)di-3,1-propanediyl]bis[2-methoxyphenol] (9CI)
MF (C24 H38 O5 Si2 . C15 H16 O2 . C Cl2 O)x
CI PMS

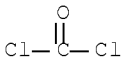
CM 1



CM 2

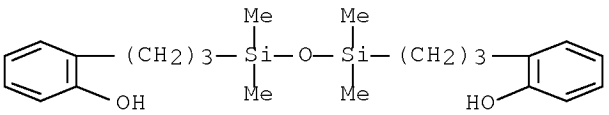


CM 3

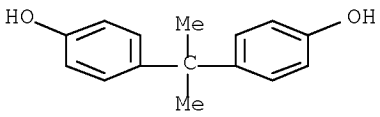


L48 52 ANSWERS REGISTRY COPYRIGHT 2008 ACS on STN
IN Carbonic dichloride, polymer with 4,4'-(1-methylethylidene)bis[phenol] and 2,2'-[(1,1,3,3-tetramethyl-1,3-disiloxanediyl)di-3,1-propanediyl]bis[phenol] (9CI)
MF (C22 H34 O3 Si2 . C15 H16 O2 . C Cl2 O)x
CI PMS

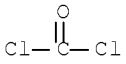
CM 1



CM 2

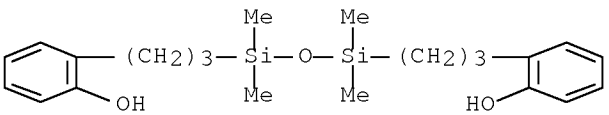


CM 3

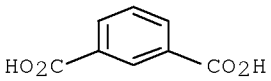


L48 52 ANSWERS REGISTRY COPYRIGHT 2008 ACS on STN
IN 1,3-Benzenedicarboxylic acid, polymer with 1,4-benzenedicarboxylic acid, 4,4'-(1-methylethylidene)bis[2-methylphenol] and 2,2'-[(1,1,3,3-tetramethyl-1,3-disiloxanediyl)di-3,1-propanediyl]bis[phenol] (9CI)
MF (C22 H34 O3 Si2 . C17 H20 O2 . C8 H6 O4 . C8 H6 O4)x
CI PMS

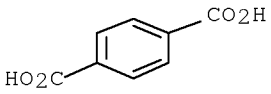
CM 1



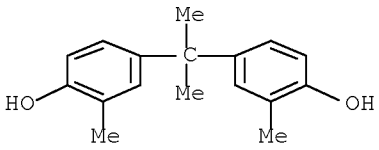
CM 2



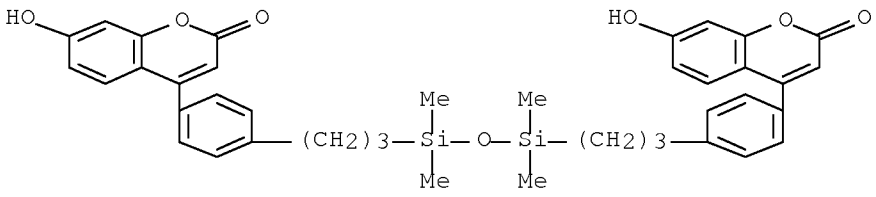
CM 3



CM 4



L48 52 ANSWERS REGISTRY COPYRIGHT 2008 ACS on STN
IN 2H-1-Benzopyran-2-one, 4,4'-[(1,1,3,3-tetramethyl-1,3-disiloxanediyl)bis(3,1-propanediyl-4,1-phenylene)]bis[7-hydroxy- (9CI)
MF C40 H42 O7 Si2

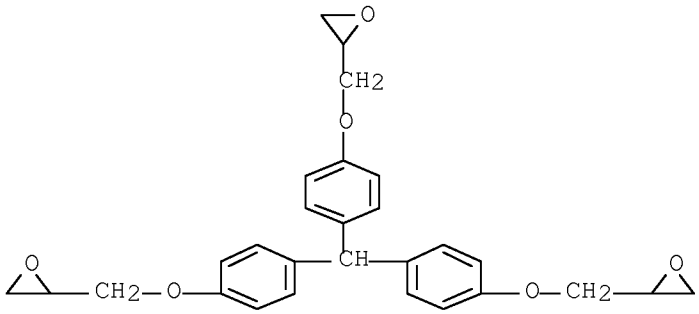


PROPERTY DATA AVAILABLE IN THE 'PROP' FORMAT

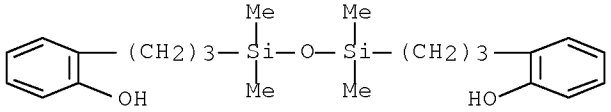
L48 52 ANSWERS REGISTRY COPYRIGHT 2008 ACS on STN
IN Phenol, 2,2'-[(1,1,3,3-tetramethyl-1,3-disiloxanediyl)di-3,1-propanediyl]bis-, polymer with 2,2',2''-[methylidynetris(4,1-phenyleneoxymethylene)]tris[oxirane] (9CI)
MF (C28 H28 O6 . C22 H34 O3 Si2)x

CI PMS

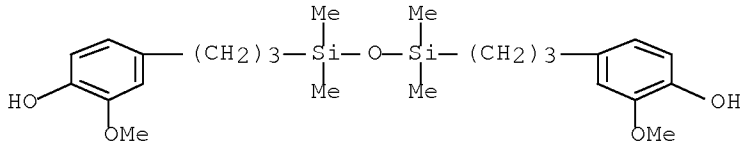
CM 1



CM 2



L48 52 ANSWERS REGISTRY COPYRIGHT 2008 ACS on STN
IN Phenol, 4,4'-[(1,1,3,3-tetramethyl-1,3-disiloxanediyl)di-3,1-propanediyl]bis[2-methoxy- (9CI)
MF C24 H38 O5 Si2
CI COM



PROPERTY DATA AVAILABLE IN THE 'PROP' FORMAT

L48 52 ANSWERS REGISTRY COPYRIGHT 2008 ACS on STN
IN Formaldehyde, polymer with phenol and 1,1,3,3-tetramethyl-1,3-bis[3-[3-(oxiranylmethoxy)phenyl]propyl]disiloxane (9CI)
MF (C28 H42 O5 Si2 . C6 H6 O . C H2 O)x
CI PMS

CM 1

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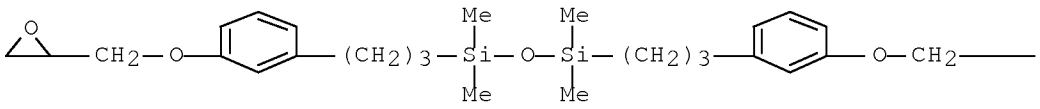

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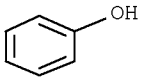
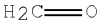
CM 2



CM 3



L48 52 ANSWERS REGISTRY COPYRIGHT 2008 ACS on STN
IN 2-Propenoic acid, 2-methyl-, (1,1,3,3-tetramethyl-1,3-disiloxanediyl)bis[3,1-propanediyl(2-methoxy-4,1-phenylene)oxy(2-hydroxy-3,1-propanediyl)] ester (9CI)
MF C38 H58 O11 Si2

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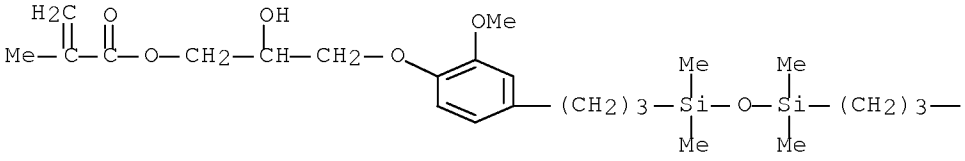
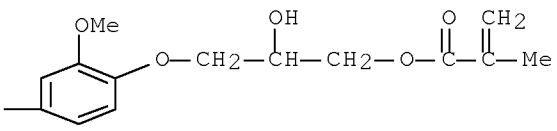


PAGE 1-B



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**PROPERTY DATA AVAILABLE IN THE 'PROP' FORMAT**


HOW MANY MORE ANSWERS DO YOU WISH TO SCAN? (1):end

=> d his

     (FILE 'HOME' ENTERED AT 13:43:50 ON 21 FEB 2008)
                SET COST OFF

     FILE 'REGISTRY' ENTERED AT 13:44:26 ON 21 FEB 2008
L1            25 S C22H34O3SI2
L2            10 S L1 AND 2/NR
L3             7 S L2 AND C6/ES
L4             4 S L3 NOT PHENOL
L5             3 S L3 NOT L4

     FILE 'HCAPLUS' ENTERED AT 13:45:21 ON 21 FEB 2008
L6            15 S L5
L7             6 S L6 AND PY<=2004 NOT P/DT
L8             8 S L6 AND (PD<=20041104 OR PRD<=20041104 OR AD<=20041104) AND P/
L9            14 S L7,L8
                 E MORITA/AU
L10            1 S E3
                 E MORITA NAME/AU
L11           55 S E4
                 E MORITA Y/AU
L12          562 S E3,E4
                 E MORITA YOSH
                 E MORITA YOSH/AU
L13          115 S E43-E45
                 E YOSHITSUGU/AU
L14            1 S E22
                 E ISSHIKI/AU
                 E ISSHIKI M/AU
L15          134 S E3
L16          265 S E20,E20
L17           26 S E26
                 E MINORU/AU
L18            3 S E3
L19            3 S E13,E21
                 E UEKI/AU
                 E UEKI H/AU
L20          245 S E3,E24
                 E UEKI NAME/AU
L21            3 S E4
                 E HIROSHI/AU
L22           15 S E3
                 E HIROSHI U/AU
L23            1 S E5
                 E HIROSHI NAME/AU
L24            6 S E4
                 E TOGASHI/AU
L25            7 S E4
L26           31 S E13-E16
                 E TOGASHI NAME/AU
L27            2 S E4
                 E ATSUSHI/AU
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L28           4 S E3
L29           2 S E57
L30           2 S L6 AND L10-L29
L31           5 S L6 AND (DOW? OR CORNING?)/PA,CS,CO
                E DOW/CO
                E E103+ALL
L32           3 S L6 AND (E2+RT OR E43-E50 OR E2-E50/PA,CS)
L33           5 S L30-L32
L34          10 S L9 NOT L33

     FILE 'USPATFULL' ENTERED AT 13:52:49 ON 21 FEB 2008
L35           8 S L5

     FILE 'REGISTRY' ENTERED AT 13:53:07 ON 21 FEB 2008

     FILE 'USPATFULL' ENTERED AT 13:53:19 ON 21 FEB 2008

     FILE 'HCAPLUS' ENTERED AT 13:53:36 ON 21 FEB 2008

     FILE 'HCAPLUS' ENTERED AT 13:53:52 ON 21 FEB 2008

     FILE 'REGISTRY' ENTERED AT 13:54:59 ON 21 FEB 2008
L36             STR
L37          13 S L36 CSS SAM
L38         306 S L36 CSS FUL
                SAV TEMP L38 LOEWE578A/A
L39         303 S L38 NOT L5
L40             STR L36
L41         220 S L40 FUL SUB=L39
                SAV TEMP L41 LOEWE578B/A
L42             STR L36
L43           2 S L42 CSS SAM SUB=L41
L44          82 S L42 CSS FUL SUB=L41
                SAV TEMP L44 LOEWE578C/A
L45          54 S L44 AND PMS/CI
L46          28 S L44 NOT L45
L47          31 S L45 NOT (N OR S OR P)/ELS
L48          52 S L44 NOT (N OR S OR P)/ELS

     FILE 'REGISTRY' ENTERED AT 14:03:09 ON 21 FEB 2008

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